

[SCRIBE LINES FOR INCREASING WAFER UTILIZABLE AREA]

Abstract of Disclosure

Scribe lines for increasing a wafer utilizable area are provided. The scribe lines include at least a first scribe line arranged in a first direction in a first gap of a plurality of dies, and at least a second scribe line arranged in the first direction in a second gap of the dies. The first scribe line includes at least an alignment mark or a test key, therefore having a width greater than a width of the second scribe line that is provided for dicing a wafer into a plurality of individual dies. In addition, the scribe lines further include a plurality groups of scribe lines arranged in different directions, and each group of the scribe lines may have various scribe line widths.

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